

KH409

Polyurethane Hot Melt

Description

Krylex KH409 is a one component reactive polyurethane hot melt. It is solid at room temperature. This is a low viscosity and temperature adhesive. After being applied warm the product will cool to allow immediate handling. Upon further exposure to ambient humidity Krylex KH409 will achieve high strength bonds and excellent environmental resistance.

Parameter Setting

The following data is the best data obtained from repeated adjustments according to the production requirements. Different users, due to different production equipment, may need to reset some data. The following data is for reference only.

Product Features

- After jetting, the glue is smooth on surface.
- After jetting, the thickness of the glue line is 0.10mm±0.02mm, and the width is 0.85mm±0.05mm.
- Higher green strength with a short or no holding time.
- Excellent heat resistance and solvent resistance.
- Excellent high temperature and low temperature resistance.

Distance of the Jetting Valve from the Touch Screen:	2mm
Temperature of Jetting Valve:	130-145°C
The flow Temperature:	120°C
Syringe Temperature:	110°C
Pulse time:	0.72ms
Cycle time:	6.5ms
Air Pressure:	0.5MPa
Speed:	50mm/s

Technical Features

Typical Uncured Properties

Color:	Black solid
Solid Content:	100%
Specific Gravity @ 25°C	1.1
Viscosity (Brookfield HBTD 10rpm):	@100°C 3000±1000 mPa
Open Time (1mm line):	1-2 minutes
Application Temperature:	100°C-130°C

Typical Cured Properties

Light Blocking:	OD Value 3.0
Coefficient of Thermal Expansion:	168.2µm/ (mK)
Coefficient of Thermal Conductivity:	0.32 W/ (mK)
Specific Heat:	2.80KJ/ (Kg.K)
Elongation, at break:	>650%
Tensile Modulus:	>250MPa
Tensile Strength (1 min):	>1.2 MPa
Tensile Shear Strength (24hr):	>8.0 Mpa



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Instructions for Use

For best results, ensure parts are clean, dry and free from oil and grease, although good bonds can still be achieved on 'as received' or slightly oily parts. The temperature of substrate should not be lower than 20°C. Low temperature will shorten the open time and cause the bonding failure. If needed, pre-heating of the substrate is recommended. Dispense bead of product onto substrate. Mate opposite substrate within recommended open time. Allow for handling strength to be achieved.

Storage

Optimal storage conditions are between 15°C to 30°C and stored in original sealed foil bag. Storage outside this temperature range can adversely affect product properties and may reduce the stated shelf life.

General Information

For safe handling of this product consult the Safety Data Sheet.

Notes

The data contained in this data sheet may be reported as typical value and/or range. Values are based on actual test data and area verified on a regular basis.

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